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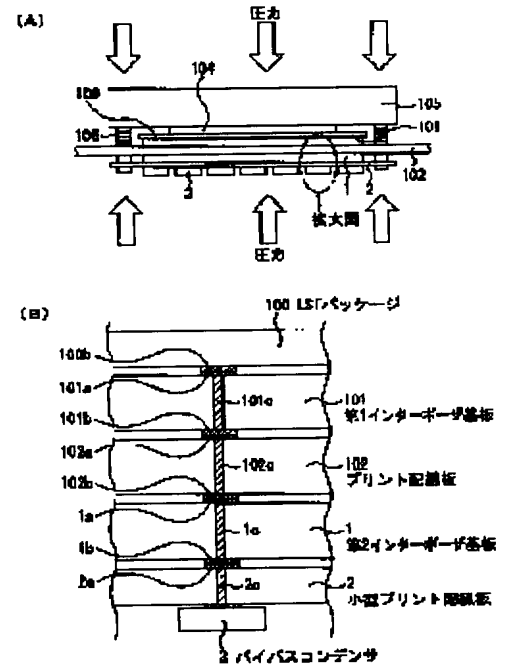
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(54) MOUNTING STRUCTURE OF LSI PACKAGE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a mounting structure of an LSI package in which the bypass capacitor in the LSI package can be disposed closely to the package.

SOLUTION: An LSI package 100, a first interposer board 101, a first printed wiring board 102 with a conduction material, a second interposer board 1, and a second wiring board 2 are stacked at a predetermined position and connected conductively by applying pressure by means of a screw 106 with a spring. According to the structure, a bypass capacitor 3 can be disposed closely to the LSI package 100.



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